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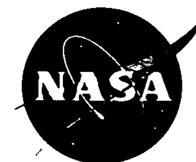
NASA TECH BRIEF



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Packaging of Electronic Modules

A study has been made of design approaches that can be taken toward optimizing the packaging of electronic modules (such as cordwood modules and printed circuit cards) with respect to size, shape, component orientation, interconnections, and structural support. The study gives consideration to the geometry of two- and three-dimensional modular arrays from the standpoint of implementing their subassembly and packaging by simple automatic machines.

Notes:

1. The study does not present a solution to specific packaging problems, but rather delineates the factors that should be considered in efforts to achieve optimum packaging designs.
2. Inquiries concerning this study may be directed to:

   Technology Utilization Officer
   Jet Propulsion Laboratory
   4800 Oak Grove Drive
   Pasadena, California 91103
   Reference: B66-10664

Patent status:

No patent action is contemplated by NASA.

Source: Leonard Katzin
(JPL-801)

Category 01

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